Package Type	PTVS10-xxxC-M		
Product Line	Semiconductor products		
Compliance Date	20th Jan 2017		
RoHS Compliant	Yes	MSL	Level 1

No.	Construction Element (subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Encapsulation	Epoxy resin	1.9662	Amorphous Silica	60676-86-0	89.50	40.80	45.58
				Solid Epoxy Resin 1	Proprietary	3.20	1.46	
				Solid Epoxy Resin 2	Proprietary	2.40	1.09	
				Phenol Resin	Proprietary	4.10	1.87	
				Crystalline Silica	14808-60-7	0.50	0.23	
				Carbon Black	1333-86-4	0.30	0.13	
2	Leadframe	Copper Alloy	0.5920	Copper	7440-50-8	97.44	13.38	13.73
				Iron	7439-89-6	2.35	0.32	
				Other, not to declare	-	0.21	0.03	
3	Electrodes	Copper Alloy	1.1944	Copper	7440-50-8	99.50	27.55	27.69
				Other, not to declare	-	0.50	0.14	
4	Clip	Copper Alloy	0.1181	Copper	7440-50-8	99.50	2.73	2.74
				Other, not to declare	-	0.50	0.01	
5	Chip	Silicon	0.2274	Silicon	7440-21-3	89.01	4.69	5.27
				Aluminum	7429-90-5	4.19	0.22	
				Nickel	7440-02-0	6.49	0.34	
				Gold	7440-57-5	0.31	0.02	
6	Die Attach	Solder	0.1939	Lead*	7439-92-1	92.50	4.16	4.50
				Tin	7440-31-5	5.00	0.23	
				Silver	7440-22-4	2.50	0.11	
7	Terminal Finish	Tin	0.0212	Tin	7440-31-5	100.00	0.49	0.49
		Total Weight	4.3132					

*** 7(a) Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)**

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